

**• General Description**

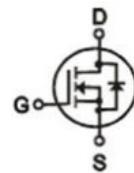
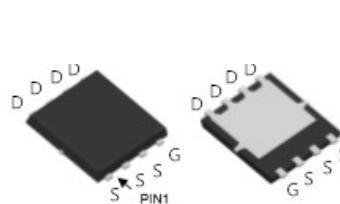
It combines advanced MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- Advance device construction
- Low $R_{DS(ON)}$ to minimize conduction loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- Synchronous Rectification for AC-DC/DC-DC converter
- Power Tools

• Product Summary $V_{DS} = 60V$ $R_{DS(ON)} = 5.2m\Omega$ $I_D = 80A$ 

DFN5 x 6

• Ordering Information:

Part NO.	ZMS052N06N
Marking	ZMS052N06
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

• Absolute Maximum Ratings ($T_c = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D @ T_c = 25^\circ C$	80	A
	$I_D @ T_c = 75^\circ C$	61	A
	$I_D @ T_c = 100^\circ C$	50	A
Pulsed Drain Current ^①	I_{DM}	240	A
Total Power Dissipation	$P_D @ T_c = 25^\circ C$	85	W
Total Power Dissipation	$P_D @ T_A = 25^\circ C$	3.4	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Storage Temperature	T_{STG}	-55 to 150	$^\circ C$
Single Pulse Avalanche Energy	E_{AS}	280	mJ

**•Thermal resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}			1.5	° C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	37	° C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	° C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	60			V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250uA	1.5		2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =0.8 BV _{DSS} , V _{GS} =0V			1.0	uA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±20V ,V _{DS} =0V			±100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =10A		5.2	6.5	mΩ
		V _{GS} =4.5V, I _D =5A		6.8	8.5	mΩ
Forward Transconductance	g _{FS}	V _{DS} =25V, I _D =10A	16			s
Source-drain voltage	V _{SD}	I _S =10A			1.28	V

•Dynamic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz, V _{DS} =25V	-	1910	-	pF
Output capacitance	C _{oss}		-	1070	-	
Reverse transfer capacitance	C _{rss}		-	22	-	
Gate Resistance	R _g	f = 1MHz		2.1		Ω
Total gate charge	Q _g	V _{DD} = 15V I _D = 5A V _{GS} = 10V	-	24	-	nC
Gate - Source charge	Q _{gs}		-	5	-	
Gate - Drain charge	Q _{gd}		-	3.3	-	
Turn-ON Delay time	t _{D(on)}	V _{GS} =10V, V _{DS} =15V R _G =6Ω, I _D =15A		8.5		ns
Turn-ON Rise time	t _r			7.5		ns
Turn-Off Delay time	t _{D(off)}			38		ns
Turn-Off Fall time	t _f			8		ns



Reverse Recovery Time	t_{RR}	$V_{DD} = 20 \text{ V}$, $dI_S/dt = 100 \text{ A}/\mu\text{s}$, $I_S = 30 \text{ A}$	22		ns
Reverse Recovery Charge	Q_{RR}		80		nC

Note: ① Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$;

Fig.1 Gate-Charge Characteristics

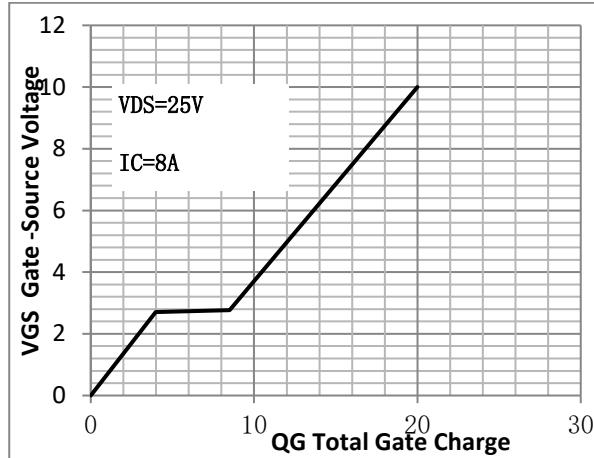


Fig.2 Capacitance Characteristics

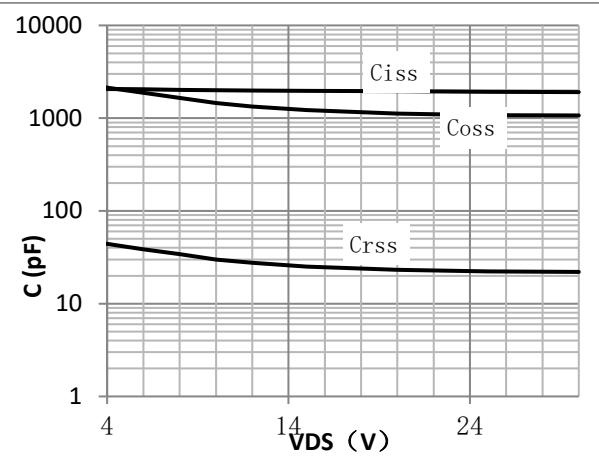


Fig.3 Power Dissipation

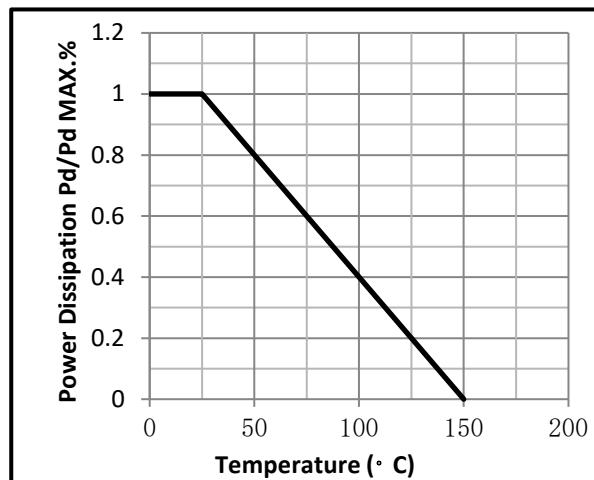


Fig.4 Typical output Characteristics

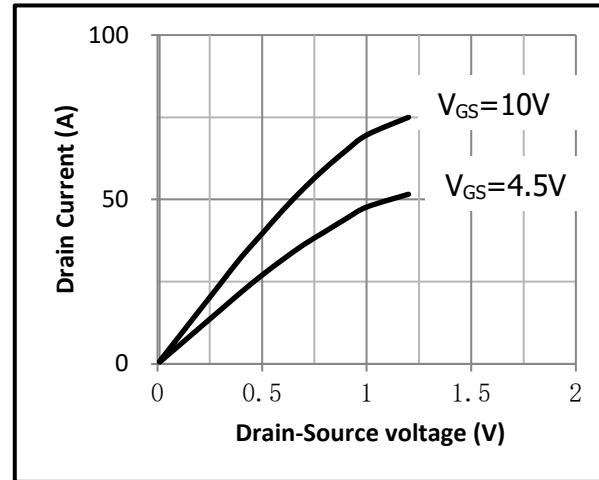




Fig.5 Threshold Voltage V.S Junction Temperature

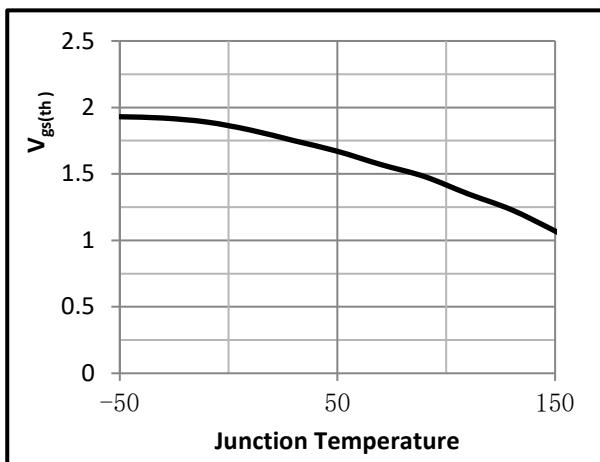


Fig.6 Resistance V.S Drain Current

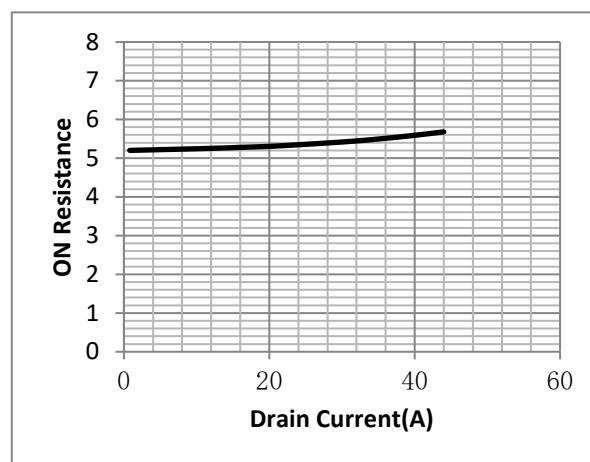


Fig.7 On-Resistance VS Gate Source Voltage

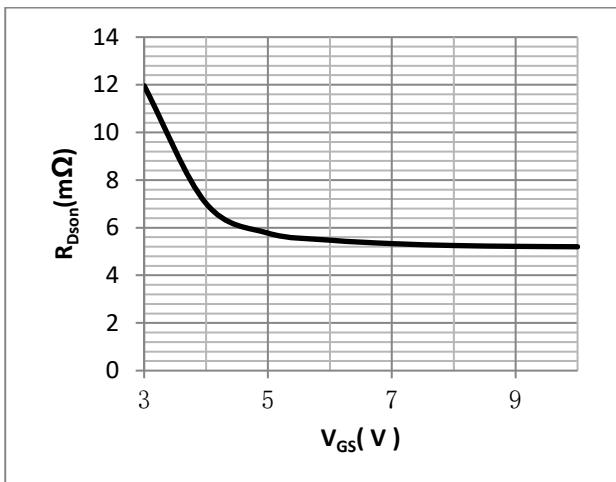


Fig.8 On-Resistance V.S Junction Temperature

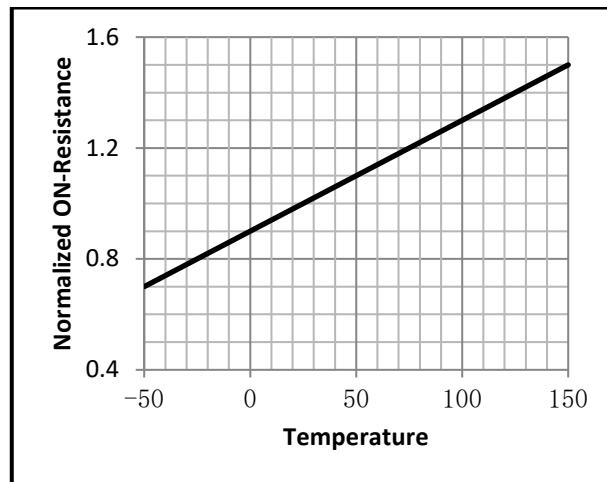


Fig.9 SOA Maximum Safe Operating Area

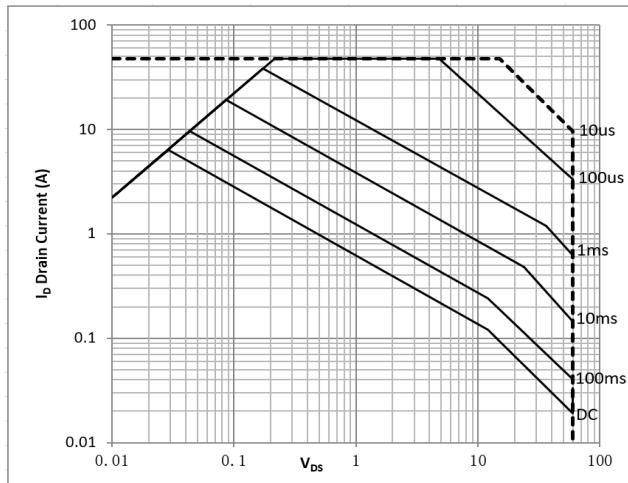


Fig.10 ID-Junction Temperature

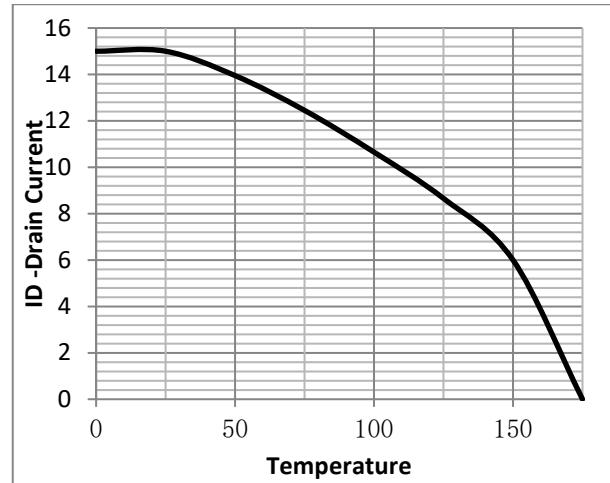


Fig.11 Switching Time Measurement Circuit

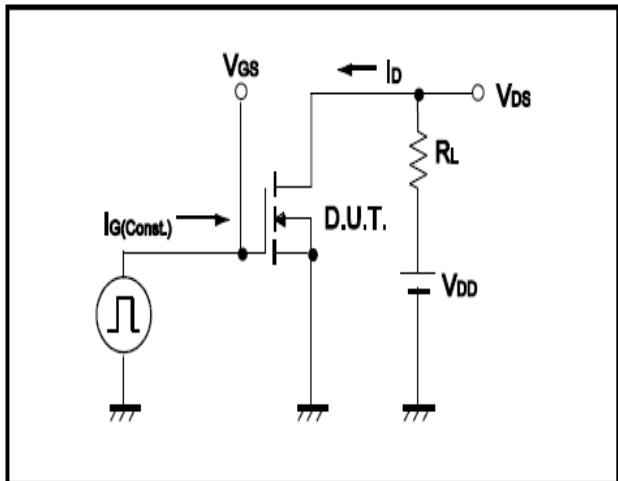


Fig.12 Gate Charge Waveform

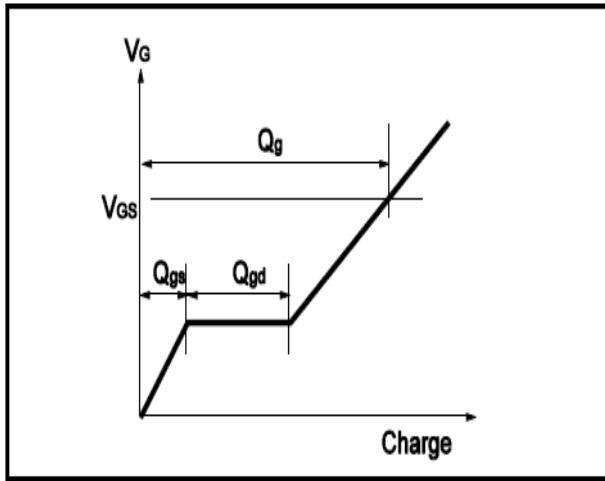


Fig.13 Switching Time Measurement Circuit

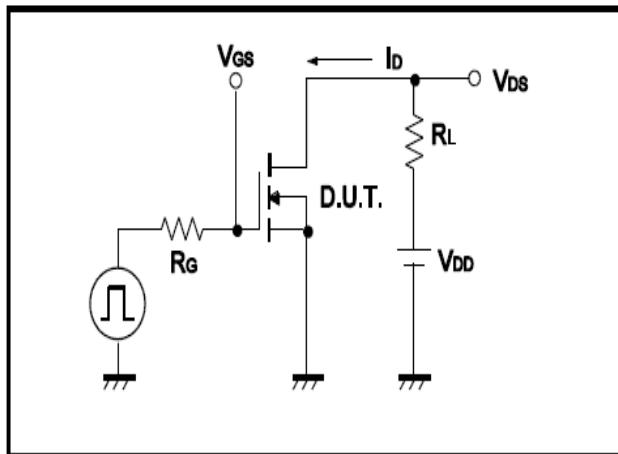
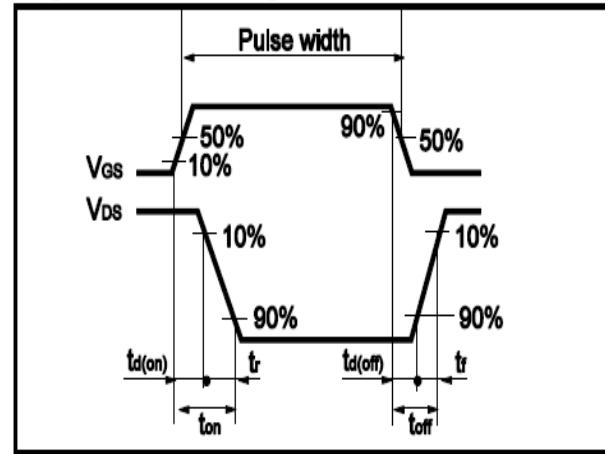


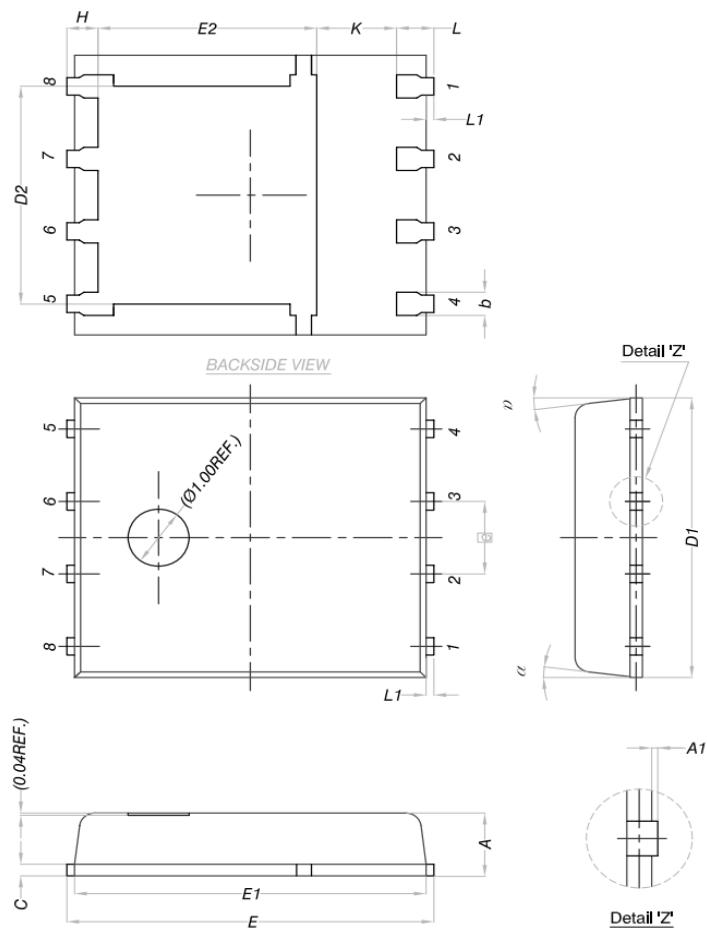
Fig.14 Gate Charge Waveform





•Dimensions (DFN5x6)

Unit: mm



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
α	0°	-	12°